

10A



**10B**



FIG.2A

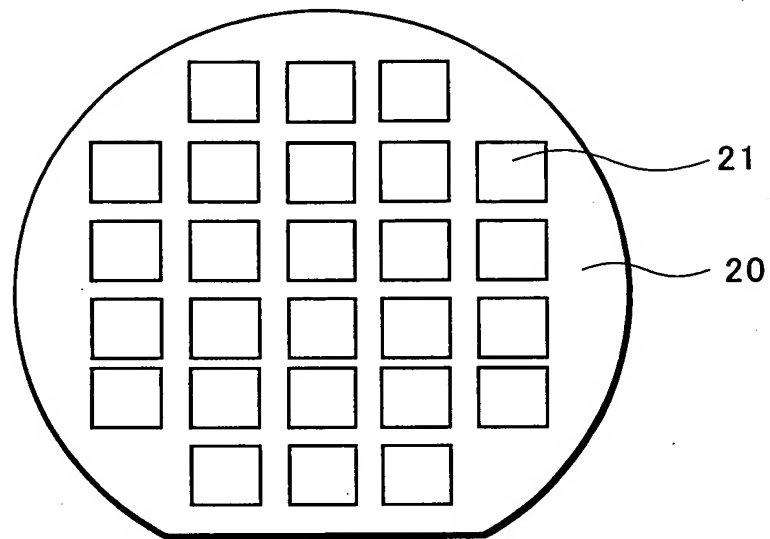


FIG.2B

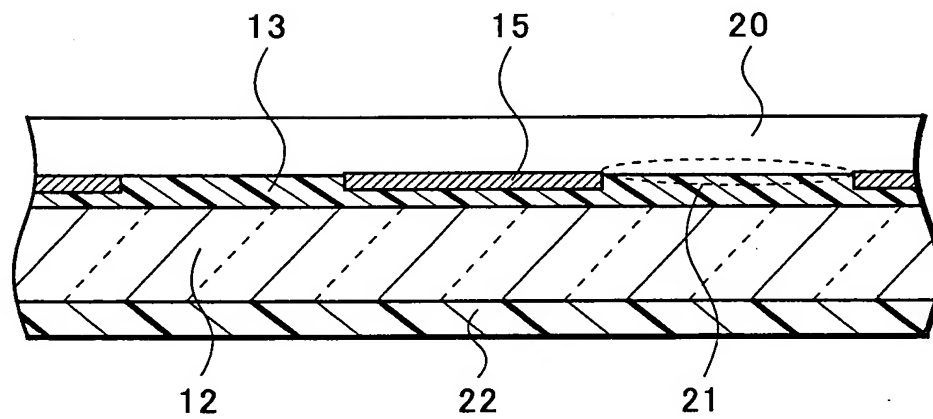


FIG.3A

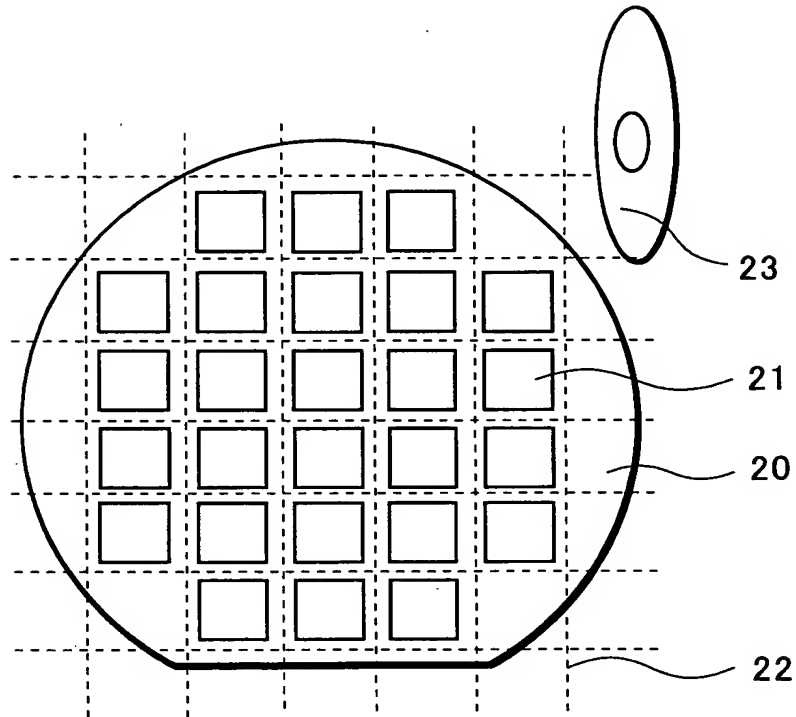


FIG.3B

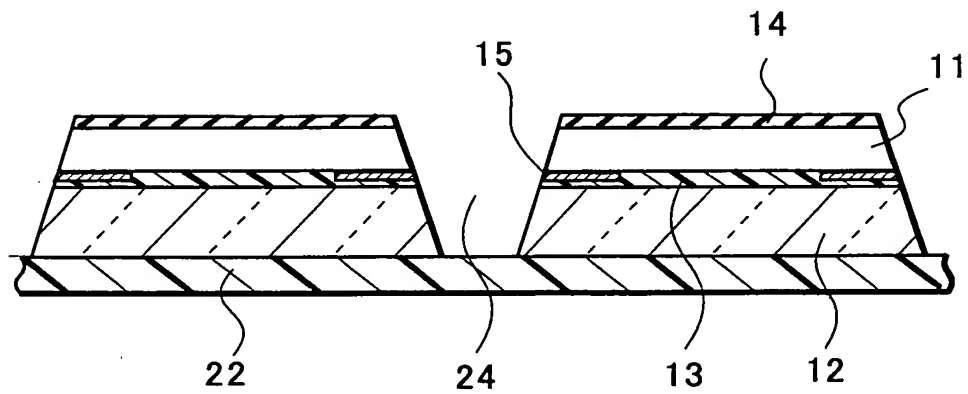


FIG.4A

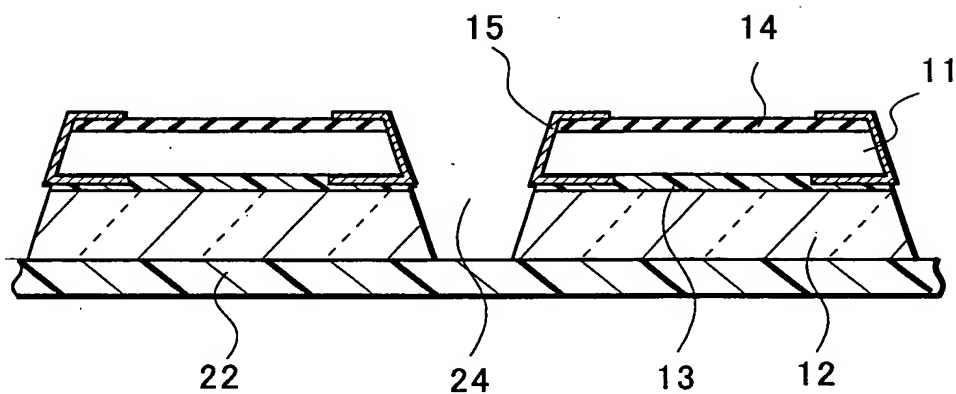


FIG.4B

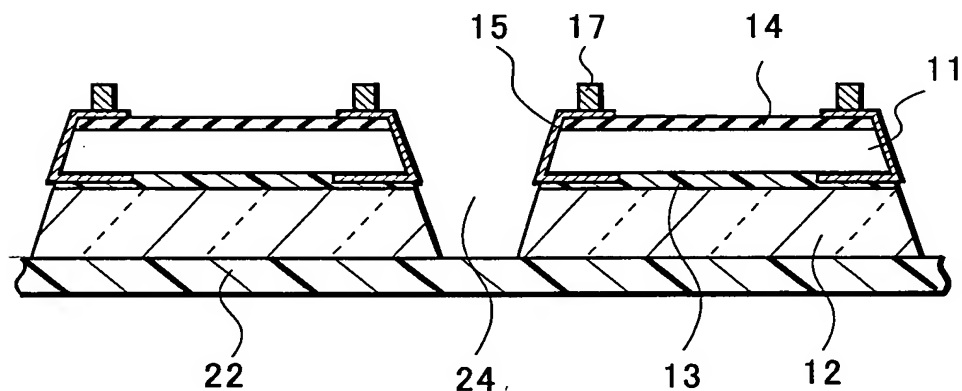


FIG.5A

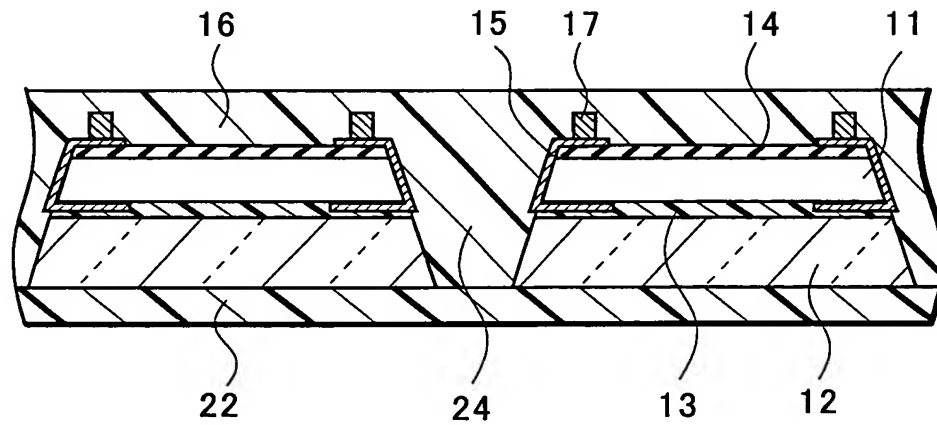


FIG.5B

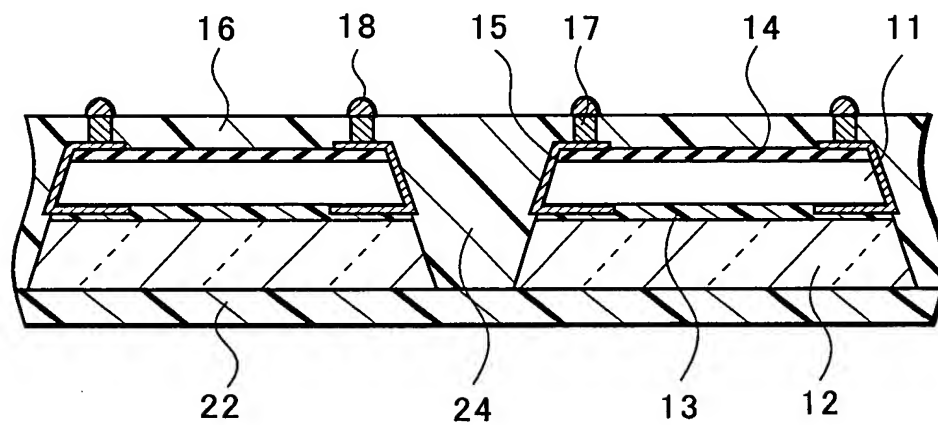


FIG.5C

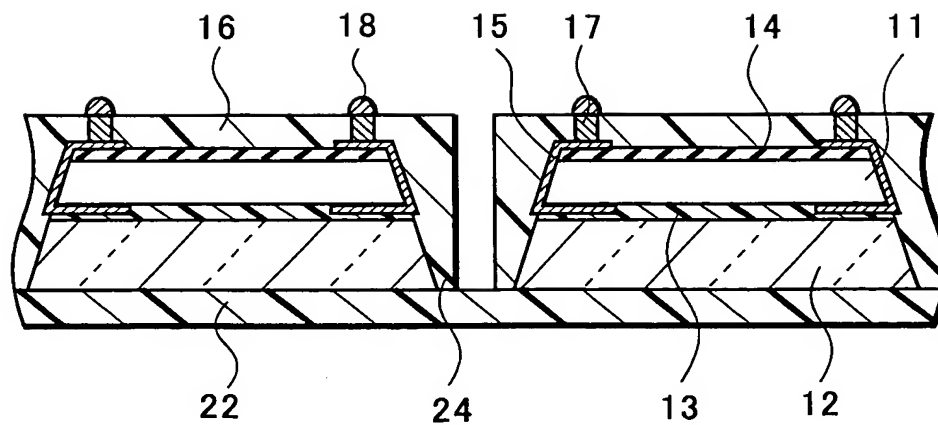


FIG.6A

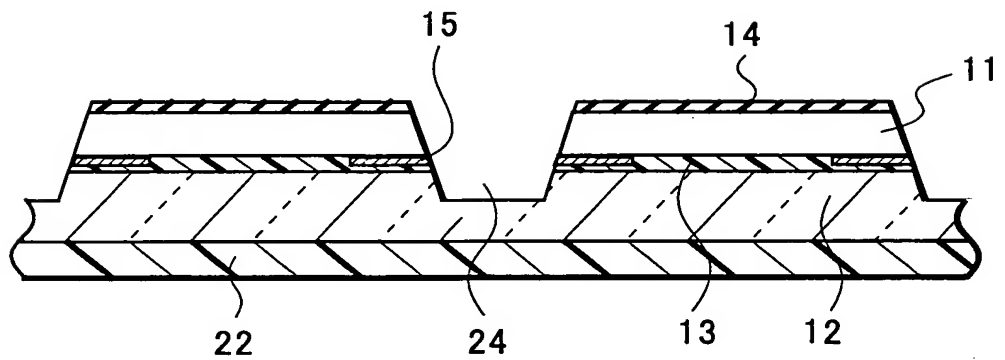


FIG.6B

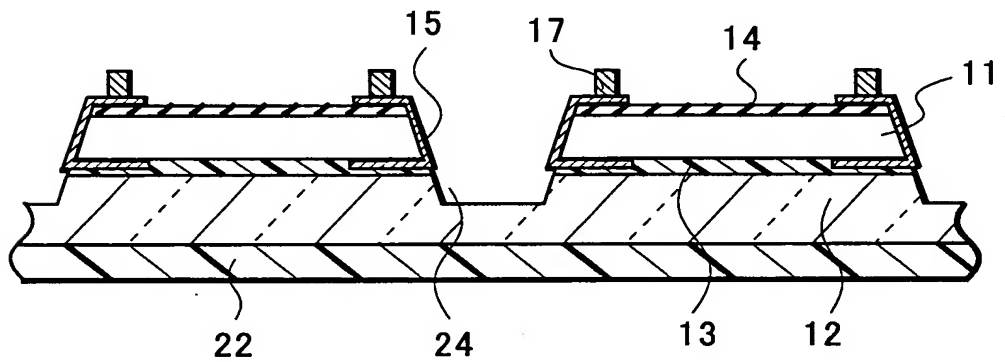


FIG.6C

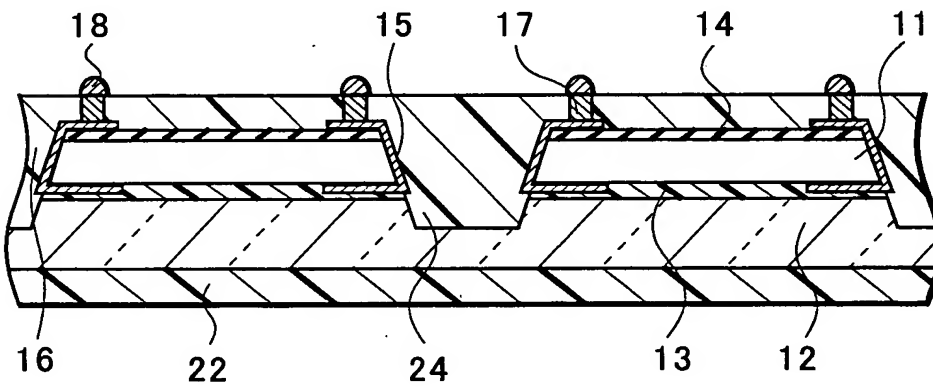
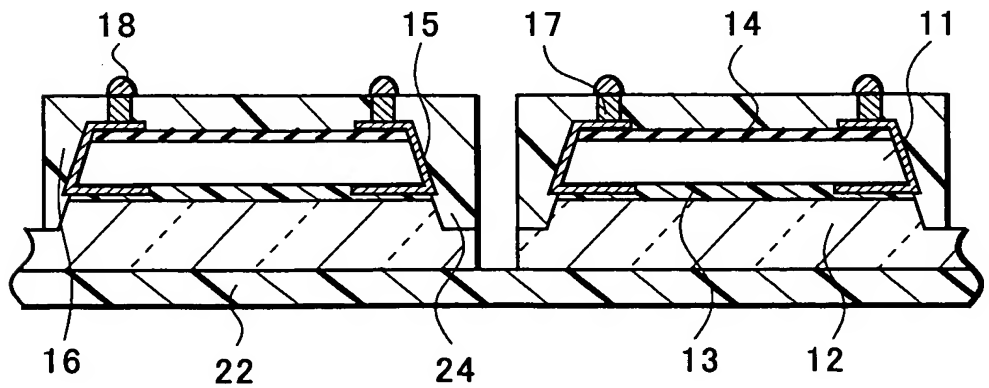


FIG.6D



A cross-sectional view of a semiconductor device. A central rectangular component (69) is mounted on a substrate (68). The component (69) has two electrical contacts (67) on its top surface, which are connected to a central pad (72) on the substrate. Two other electrical contacts (65) are located on the left and right sides of the substrate, connected to side pads (70 and 71). The entire assembly is surrounded by a protective layer (66). The top surface of the substrate is labeled 73, and the side surface is labeled TH.